IN THE CLAIMS:

Please amend claim 13 as follows:

13. (Twice Amended) A method of manufacturing a semiconductor device, comprising:

adhering on an adhesive side of an adhesive tape chips separated by dicing a wafer; and

repeating a step of peeling a chip off the adhesive tape to sequentially peel the chips off the adhesive tape, wherein the step of peeling a chip off the adhesive tape comprises:

blowing inert gas at a high temperature to the adhesive tape so as to decrease adhesion of the adhesive tape;

thrusting the chip using pins from a back side of the adhesive tape with the adhesive tape between the chip and the pins, and keeping the pins at a peak position for an amount of time to facilitate peeling the chip off the adhesive tape, wherein the pins do not pierce the adhesive tape;

descending a collet from the adhesive side of the adhesive tape to contact and suck the chip when the chip is peeled off the adhesive tape; and

picking the chip up by ascending the collet.

REMARKS

By the present Amendment, Applicants have amended claim 13 to more appropriately define their invention. Support for the added step in new claim 13 can be found in the specification, for example, from page 24, line 7 to page 25, line 22.

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